

ABSTRACT OF THE DISCLOSURE

Accumulating spaces for conductive particles are formed in gaps of wiring patterns for conductive wirings which are disposed
5 on a surface of a supporting body. When interconnecting a pair of interconnection objects having the respective wiring patterns via an anisotropic conductive film thereon due to a thermocompression bonding, the conductive particles to be flown-out into the gaps by the thermocompression bonding are allowed to escape into the
10 accumulating spaces, so that an over-density of the conductive particles can be prevented to avoid a shortage in the wiring patterns.